

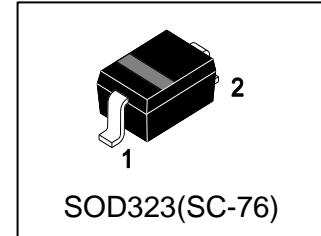
LMDL914T1G

S-LMDL914T1G

High –Speed Switching Diode

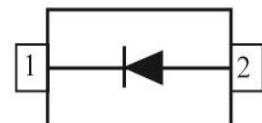
1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMDL914T1G	5D	3000/Tape&Reel
LMDL914T3G	5D	10000/Tape&Reel



3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Reverse Voltage	VR	100	Vdc
Forward Current	IF	200	mAdc
Peak Forward Surge Current	IFMS	500	mAdc

4. THERMAL CHARACTERISTICS

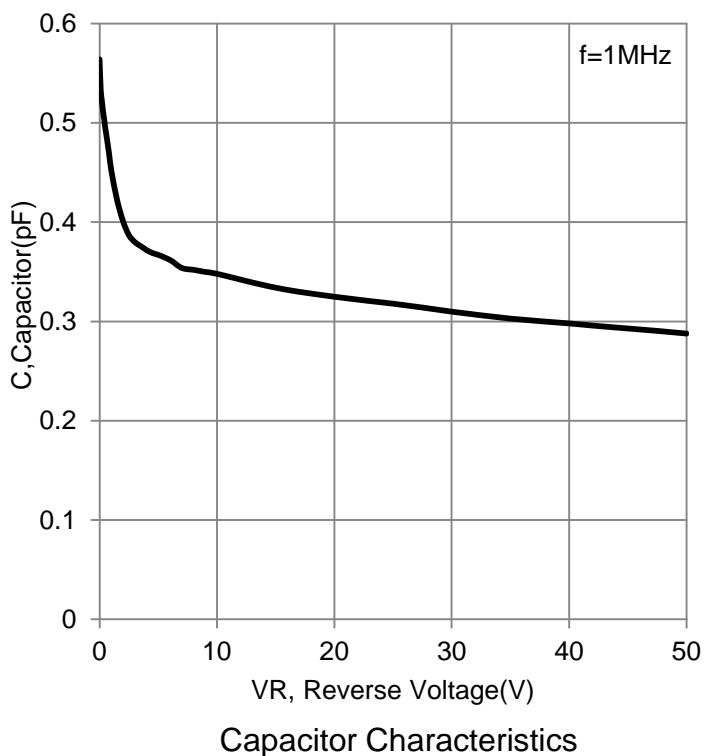
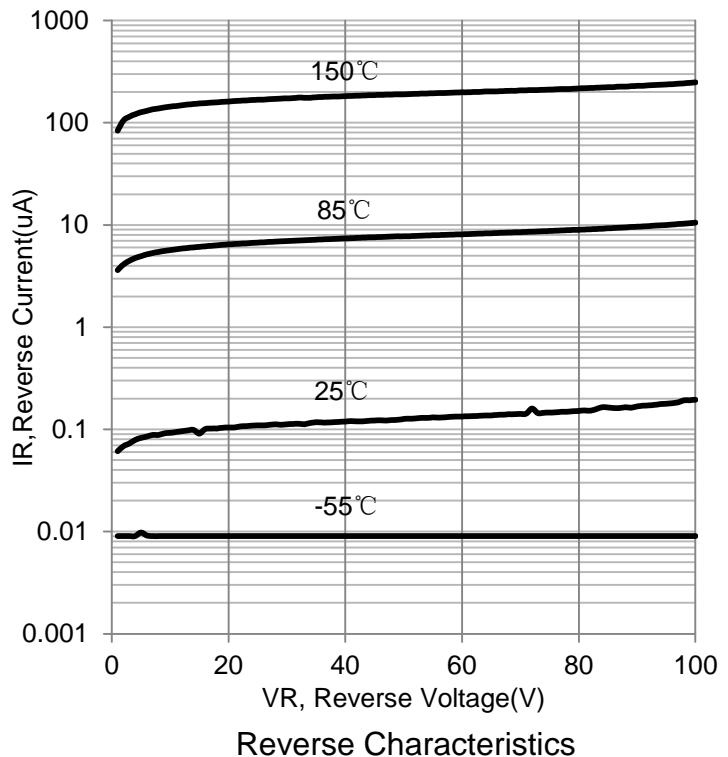
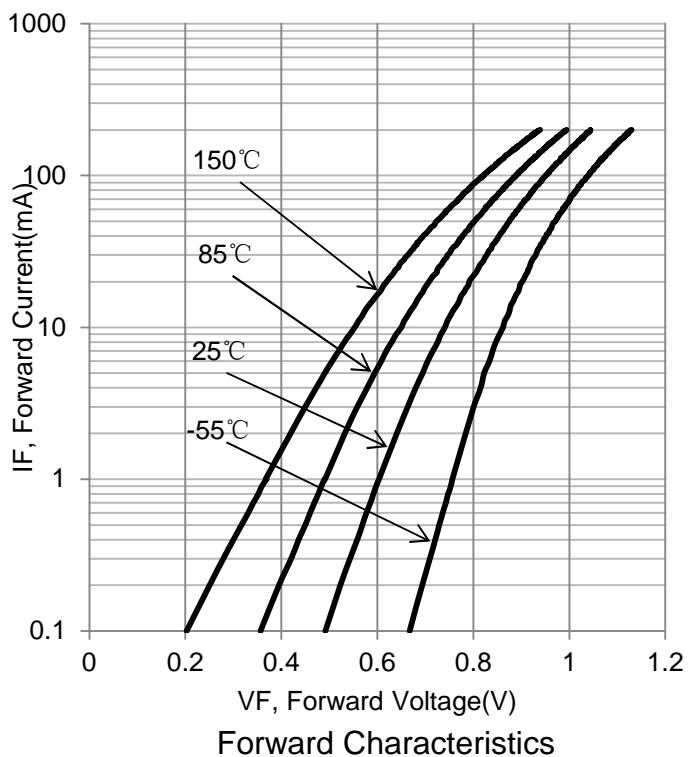
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	R _{θJA}	635	°C/W
Junction and Storage temperature	T _{J,Tstg}	-55~+150	°C

1. FR-4 = 1.0×0.75×0.062 in.

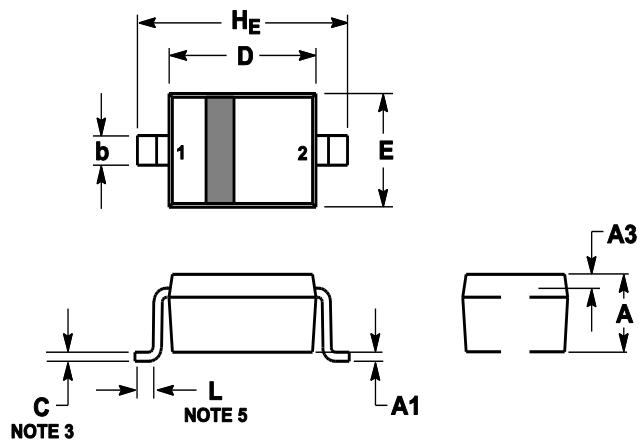
5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage (IR = 100µAdc)	VBR	100	-	-	V
Reverse Voltage Leakage Current (VR = 20Vdc) (VR = 75Vdc)	IR	-	-	25 5	nA µA
Diode Capacitance (VR = 0, f = 1.0 MHz)	CT	-	-	4	pF
Forward Voltage (IF = 10 mAdc)	VF	-	-	1	V
Reverse Recovery Time (IF = IR = 10 mAdc)	trr	-	-	4	ns
Non-Repetitive Peak Forward Current (square wave; Tj=25 °C prior to surge t=1 µs) (t=1ms) (t=1s)	IFSM	- - -	- - -	4 1 0.5	A

6. ELECTRICAL CHARACTERISTICS CURVES



7. OUTLINE AND DIMENSIONS



Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H _E	2.3	2.5	2.7	0.09	0.098	0.105

8. SOLDERING FOOTPRINT

